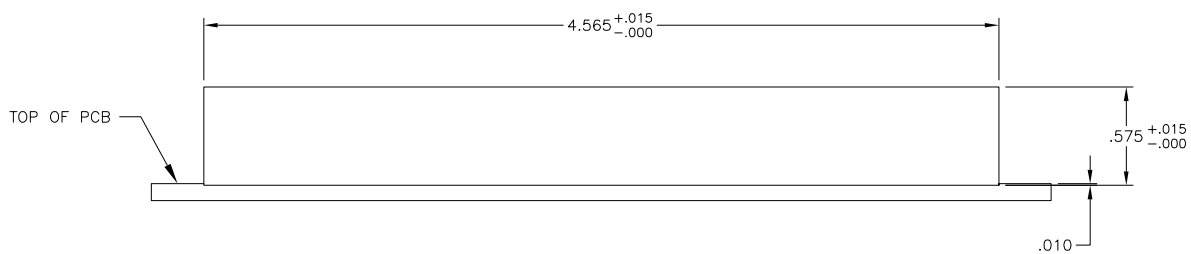
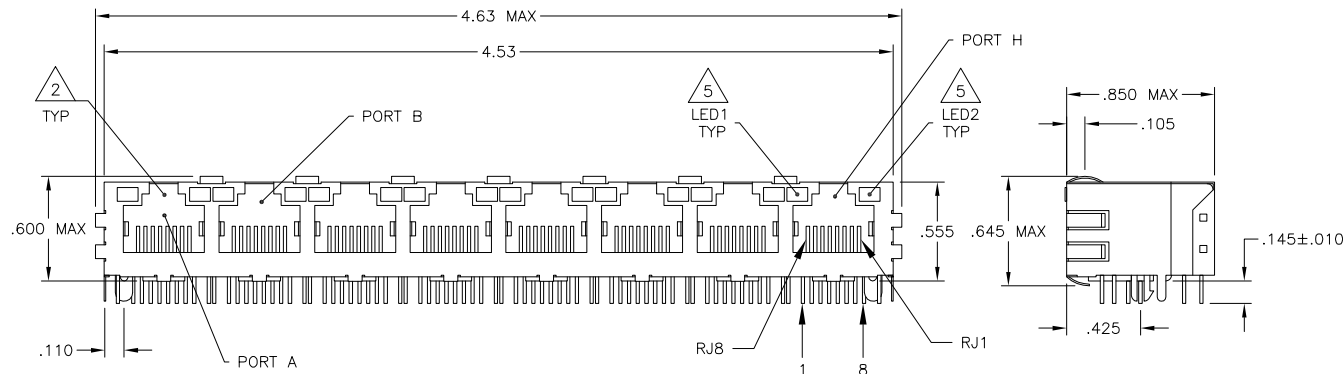
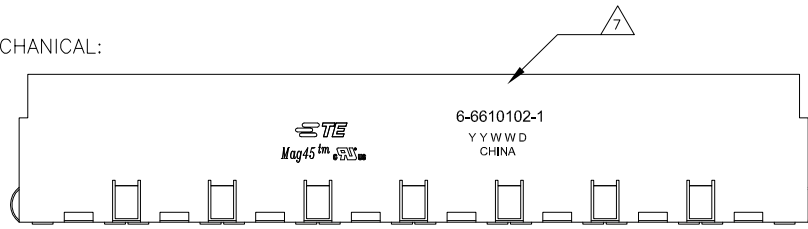


LOC	DATE	REVISIONS	DATE	BY	APP'D
AA	22				
D	REV PER	ECO-09-025671	16NOV2009	QL	LR
E	ECO-11-013353		20MAY2011	EL	LR

MECHANICAL:



1X8 SUGGESTED PANEL CUTOUT

1. HOUSING - THERMOPLASTIC PET POLYESTER FLAMMABILITY RATING UL 94V-0.
SHIELD - .010" THICK C26800 BRASS PREPLATED WITH 30μINCH MIN SEMI-BRIGHT NICKEL. SOLDER TABS POST DIPPED WITH 100μINCH MIN SAC SOLDER.
MOD JACK CONTACTS - 0.0157 X 0.018" PHOSPHOR BRONZE. 50μINCH MIN OVERALL NICKEL UNDERPLATE WITH SELECT 50μINCH MIN HARD GOLD FINISH PLATE. SOLDER TAILS WITH 100μINCH MIN MATTE TIN AND/OR SAC SOLDER DIP.
LIGHT EMITTING DIODE(LED) - DIFFUSED EPOXY LENS, .020" X .020" CARBON STEEL WIREFRAME LEADS PRE-PLATED WITH 80μINCH SILVER OVER 40μINCH NICKEL UNDERPLATE OVER 40μINCH COPPER UNDERPLATE. POST-PLATED WITH 100μINCH MIN MATTE TIN AND/OR SAC SOLDER DIP OR PURE TIN SOLDER DIP.
2. RJ45 JACK CAVITY CONFORMS TO FCC RULES AND REGULATIONS PART 68, SUB PART F.
3. MAGNETICS
-IMPEDANCE: 100 OHMS
-TURNS RATIO (CHIP-CABLE): TX = 1:1, RX = 1:1
-OPEN CIRCUIT INDUCTANCE (OCL): 350μH MIN @100kHz, 0.1VRMS, 8mA DC BIAS FROM 0°C TO 70°C, TX AND RX
-PERFORMANCE @ 25°C:
INSERTION LOSS (IL): 1.1dB MAX FROM 0.5MHz TO 100MHz
RETURN LOSS (RL): 18dB MIN FROM 0.5MHz TO 30MHz
18-20LOG(f/30dB) MIN FROM 30.1MHz TO 60MHz
12dB MIN FROM 60.1MHz TO 80MHz
CROSSTALK ATTENUATION: 35dB MIN FROM 0.5MHz TO 40MHz
33-20*LOG(f/50dB) MIN FROM 40.1MHz TO 100MHz
COMMON MODE REJECTION RATIO (CMRR): 30dB MIN FROM 0.5MHz TO 100MHz
-ISOLATION VOLTAGE: 2250VDC (MAX) FOR 60 SECONDS WITH A RISE TIME OF 500V/SEC AND WITH ALL PORTS CONNECTED.
4. OPERATING TEMPERATURE: FROM 0°C TO +70°C.
5. IF THE LED WITH 250 OHM RESISTORS, LED IS DRIVEN WITH 5V VOLTAGE AND THE MAX OPERATING CURRENT IS 20mA.
LED COLOR : DOMINANT WAVELENGTH (LD): GREEN 568 nm TYP. @ VF=5V
FORWARD CURRENT (IF): GREEN 12 mA TYP. @ VF=5V
6. INDICATED CONNECTIONS ARE FOR NIC CONFIGURATION. THE MAGNETICS ARE SYMMETRICAL AND SUPPORT OR AUTO-MDI/MDIX.
7. TE CONNECTIVITY LOGO, PART NUMBER, DATE CODE, COUNTRY OF ORIGIN AND AGENCY APPROVAL MARKING IN APPROXIMATE LOCATION SHOWN.
8. THE PART IS RECOMMENDED FOR WAVE SOLDERING PROCESS. PREHEAT TEMPERATURE IS 120°C TO 160°C, 120 SECONDS TO 180 SECONDS. PEAK WAVE SOLDERING TEMPERATURE IS 260°C MAX, 10 SECONDS MAX.

GREEN	GREEN	6-6610102-1
LED1	LED2	PART NUMBER

THIS DRAWING IS A CONTROLLED DOCUMENT.

DESIGNED BY: D. FAROLE	DATE: 10MAR2008	NAME: D. FAROLE	DATE: 10MAR2008
CHECKED BY: D. FAROLE	DATE: 10MAR2008	NAME: D. FAROLE	DATE: 10MAR2008
APPROVED BY: D. FAROLE	DATE: 10MAR2008	NAME: D. FAROLE	DATE: 10MAR2008

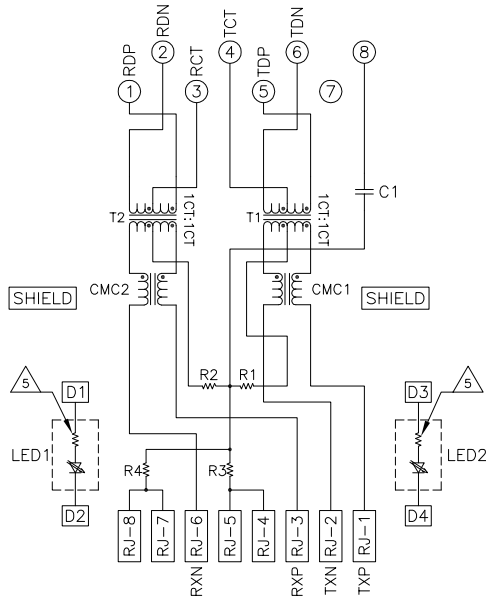
TE Connectivity

1X8 MA645(TW) MODULAR JACK, 7K2 SCHEMATIC, 726K2 SERIES CIRCUIT, DECOUPLING CAPACITOR, SHIELDED, WITH RESISTOR LEADS

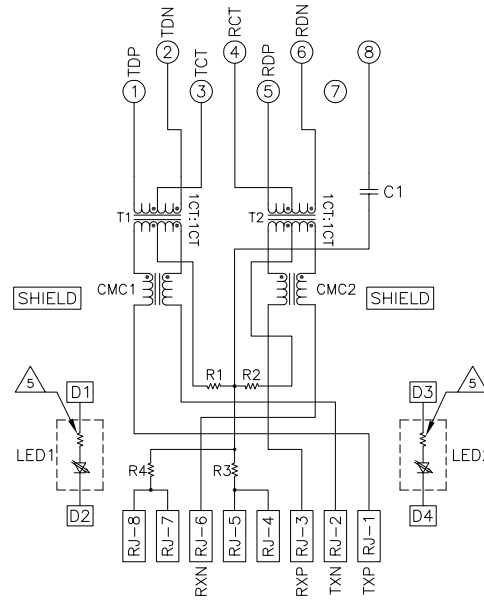
SIZE	DATE CODE	DRAWING NO	RESTRICTED TO
A1	00779	C=6610102	

CUSTOMER DRAWING SCALE: 2:1 SHEET 1 OF 2 REV F

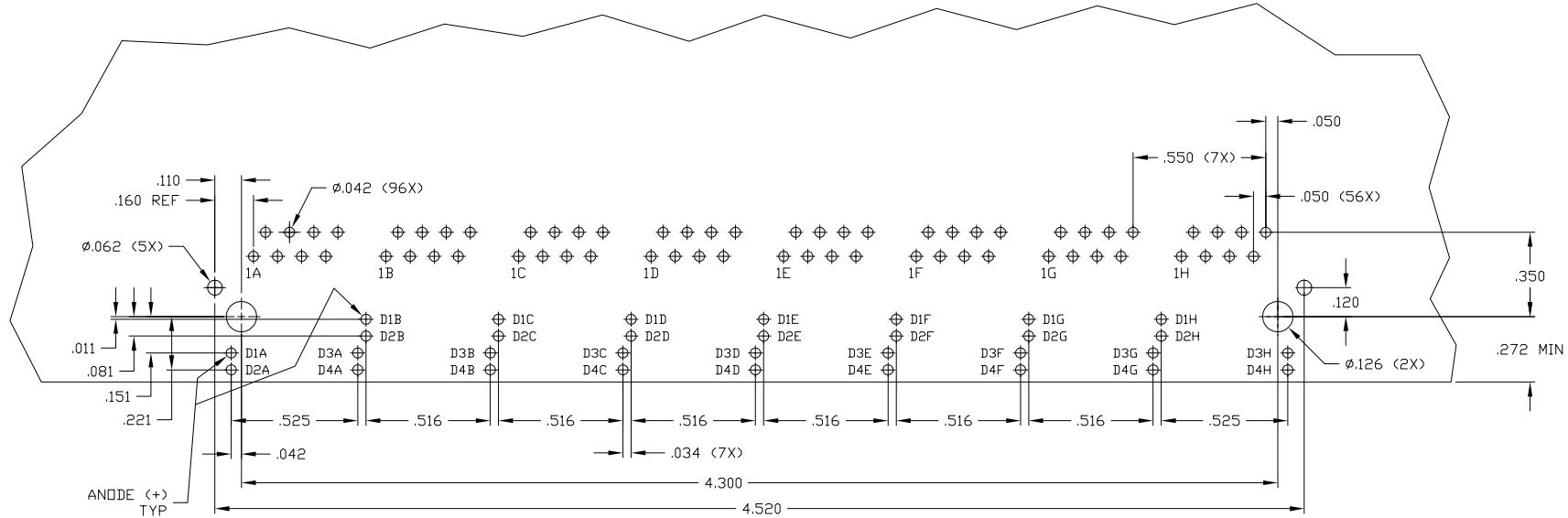
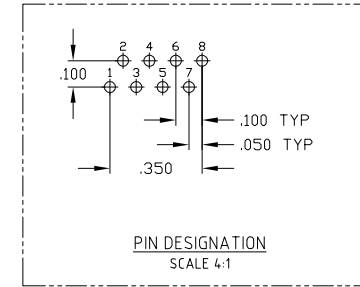
726K2 SERIES MAGNETIC CIRCUIT
PORTS 1,3,5,7



726K2 SERIES MAGNETIC CIRCUIT
PORTS 2,4,6,8



C1 = 1000pF, 2kV CAPACITOR
R1-R4 = 75 OHMS, 1/16 W RESISTORS



SUGGESTED PCB LAYOUT
(Component Side)
SCALE 4:1

THIS DRAWING IS A CONTROLLED DOCUMENT.		REV	A	FERNANDEZ-100200	DATE	10MAR2003	NAME	
DRAWN BY: D. FAROLE		CHK	D.	FAROLE	DATE	10MAR2003	NAME	
DIMENSIONS: INCHES		APP'D	D.	FAROLE	DATE	10MAR2003	NAME	
TOLERANCES UNLESS OTHERWISE SPECIFIED:		0 P.L.C.		± .005		1X8 MA645(TW) MODULAR JACK, 7K2 SCHEMATIC, 726K2 SERIES CIRCUIT, DECOUPLING CAPACITOR, SHIELDED, WITH RESISTOR LEADS		
1 P.L.C.		± .010		108-2100		APPLICATION SPEC		
2 P.L.C.		± .020		SIZE		CODE		DRAWING NO
3 P.L.C.		± .030		A1		00779		C=6610102
4 P.L.C.		± .040		MATERIAL		RESTRICTED TO		
ANGLES		± .005		FINISH		SCALE		2:1
MATERIAL		-		WEIGHT		SHEET		2 of 2
FINISH		-		CUSTOMER DRAWING		REV		F